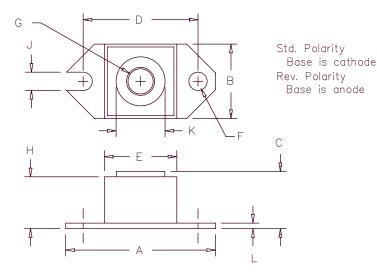
## 180 Amp Schottky Rectifier HS18135-HS18145



Dim.	Dim. Inches			Millimeter		
	Minimum	Maximum	Minimum	Maximum	Notes	
А	1.52	1.56	38.61	39.62		
В	.725	.775	18.42	19.69		
С	.605	.625	15.37	15.88		
D	1.182	1.192	30.02	30.28		
E	.745	.755	18.92	19.18	Sq.	
F	.152	.160	3.86	4.06	Sq. Dia.	
G		1/4-20	UNC-2B			
Н	.525	.580	13.34	14.73		
J	.156	.160	3.96	4.06		
K	.495	.505	12.57	12.83	Dia.	
L	.120	.130	3.05	3.30		

### HALF-PAK

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
HS18135*	181NQ035	35V	35V
HS18140*	181NQ040	40V	40V
HS18145*	181NQ045	45V	45V
	* Add Suffix R	for Reverse Polari	ty

- $\bullet$  Guard Ring Protection
- Low Forward Voltage
- 175°C Junction Temperature
- VRRM 35-45 Volts
- Reverse Energy Tested
- ROHS Compliant

Average forward current Maximum surge current Maximum repetitive reverse current Max peak forward voltage Max peak reverse current Max peak reverse current Typical junction capacitance |F(AV) 180 Amps |FSM 2500 Amps |R(OV) 2 Amps VFM 0.70 Volts |RM 150mA |RM 4mA CJ 7500pF

Electrical Characteristics

 $T_{C} = 142^{\circ}C$ , square wave,  $R_{\Theta JC} = 0.3^{\circ}C/W$ 8.3ms, half sine,  $T_{J} = 175^{\circ}C$ f = 1 kHz, 1us square wave,  $J = 25^{\circ}C$ IFM = 180A:  $T_{J} = 25^{\circ}C^{*}$ VRRM,  $T_{J} = 125^{\circ}C^{*}$ VRRM,  $T_{J} = 25^{\circ}C$ VR = 5.0V,  $T_{J} = 25^{\circ}C$ , f = 1MHz

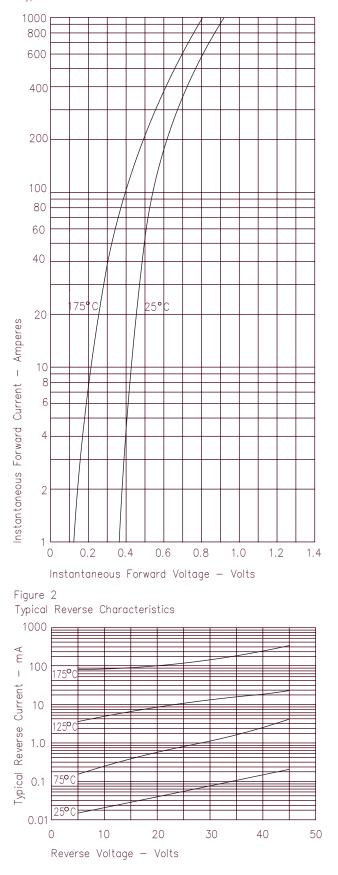
\*Pulse test: Pulse width 300µsec, Duty cycle 2%

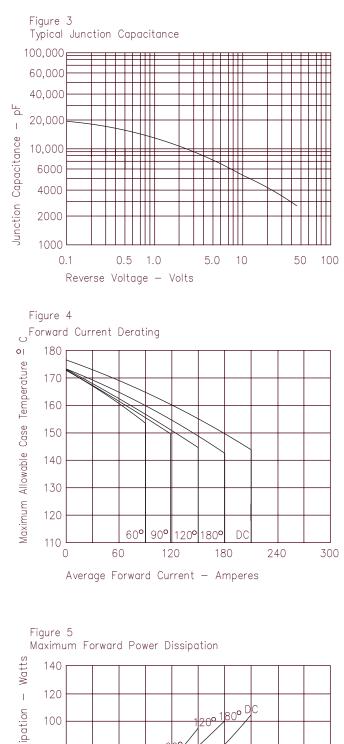
Thermal	and Mechanical	Characteristics
Storage temp range Operating junction temp range Max thermal resistance Typical thermal resistance (greased) Mounting Base Torque Terminal Torque Weight	TSTG TJ R OJC R OCS	-55°C to 175°C -55°C to 175°C 0.3°C/W junction to case 0.12°C/W case to sink 15-25 inch pounds 20-40 inch pounds 1.1 ounces (32 grams) typical

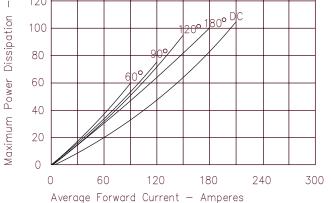


# HS18135-HS18145

Figure 1 Typical Forward Characteristics







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